

L Number	Hits	Search Text	DB	Time stamp
1	3859	438/106	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/09 16:30
2	2413	438/106	USPAT	2004/06/09 17:53
3	1411	438/107	USPAT	2004/06/09 18:07
4	1684	438/108	USPAT	2004/06/09 18:25
6	1793	438/118	USPAT	2004/06/09 18:26
-	8	"6316822"	USPAT	2004/06/09 16:29
-	7	"9802864"	EPO; JPO; DERWENT; IBM TDB	2004/06/07 18:17
-	15	"5977615"	USPAT	2004/06/07 18:47
-	3131	257/666	USPAT	2004/06/07 18:47
-	1107	257/666 and (die near pad or paddle)	USPAT	2004/06/07 19:43
-	8946	(semiconductor or die or chip or IC) with (double or both or dual) near sides	USPAT	2004/06/07 21:18
-	1176	((semiconductor or die or chip or IC) with (double or both or dual) near sides) and (flip or "C4" or solder near (ball or bump))	USPAT	2004/06/07 21:05
-	1	"5352926".PN.	USPAT	2004/06/07 20:42
-	1	"5710071".PN.	USPAT	2004/06/07 20:43
-	1	"5777386".PN.	USPAT	2004/06/07 20:43
-	1	"5969461".PN.	USPAT	2004/06/07 20:43
-	1	"5973927".PN.	USPAT	2004/06/07 20:44
-	3529	((semiconductor or die or chip or IC) with (double or both or dual) near sides) and lead	USPAT	2004/06/07 21:18
-	363	((semiconductor or die or chip or IC) with (double or both or dual) near sides) and lead and (die near pad or paddle)	USPAT	2004/06/07 21:05
-	9824	(semiconductor or die or chip or IC) near (double or both or dual)	USPAT	2004/06/07 21:19
-	1516	(semiconductor or die or chip or IC) near (double or dual)	USPAT	2004/06/07 21:48
-	1	"6020629".PN.	USPAT	2004/06/07 21:30
-	1	"6075284".PN.	USPAT	2004/06/07 21:30
-	1	"6146918".PN.	USPAT	2004/06/07 21:31
-	1	"5977624".PN.	USPAT	2004/06/07 21:32
-	1	"6150730".PN.	USPAT	2004/06/07 21:32
-	1	"6177721".PN.	USPAT	2004/06/07 21:32
-	1	"6218731".PN.	USPAT	2004/06/07 21:32
-	1	"6252298".PN.	USPAT	2004/06/07 21:32
-	2214	257/676	USPAT	2004/06/07 21:49
-	1151	257/676 and solder	USPAT	2004/06/07 21:49
-	1	"6507120".PN.	USPAT	2004/06/07 21:52
-	1	"6482680".PN.	USPAT	2004/06/07 21:52
-	1	"6303997".PN.	USPAT	2004/06/07 21:52
-	1	"6294100".PN.	USPAT	2004/06/07 21:53
-	1	"6281568".PN.	USPAT	2004/06/07 21:53
-	1	"6242281".PN.	USPAT	2004/06/07 21:53
-	1	"6229200".PN.	USPAT	2004/06/07 21:53
-	1	"6225146".PN.	USPAT	2004/06/07 21:54
-	1	"6208021".PN.	USPAT	2004/06/07 21:54
-	1	"6198171".PN.	USPAT	2004/06/07 21:56
-	1	"6143981".PN.	USPAT	2004/06/07 21:56
-	1	"6140154".PN.	USPAT	2004/06/07 21:56
-	1	"6130473".PN.	USPAT	2004/06/07 21:56
-	1	"6130115".PN.	USPAT	2004/06/07 21:56
-	1	"6084310".PN.	USPAT	2004/06/07 21:57
-	1	"6072228".PN.	USPAT	2004/06/07 21:57
-	1	"6034423".PN.	USPAT	2004/06/07 21:57
-	1	"6025640".PN.	USPAT	2004/06/07 21:57
-	1	"6001671".PN.	USPAT	2004/06/07 21:57
-	1	"5986885".PN.	USPAT	2004/06/07 21:57
-	1	"5981314".PN.	USPAT	2004/06/07 21:58
-	1	"5977630".PN.	USPAT	2004/06/07 21:58
-	1	"5977613".PN.	USPAT	2004/06/07 21:58
-	1	"5648682".PN.	USPAT	2004/06/07 22:02

-	1	"5677567".PN.	USPAT	2004/06/07 22:03
-	1	"6060769".PN.	USPAT	2004/06/07 22:03
-	1	"6208020".PN.	USPAT	2004/06/07 22:03
-	1	"5212402".PN.	USPAT	2004/06/07 22:13
-	1	"5450283".PN.	USPAT	2004/06/07 22:15
-	1	"5663593".PN.	USPAT	2004/06/07 22:15
-	1	"5731631".PN.	USPAT	2004/06/07 22:15
-	1	"5849608".PN.	USPAT	2004/06/07 22:16
-	1	"5969947".PN.	USPAT	2004/06/07 22:16
-	1	"4922321".PN.	USPAT	2004/06/07 22:37
-	1	"5334857".PN.	USPAT	2004/06/07 22:37
-	1	"5433822".PN.	USPAT	2004/06/07 22:37
-	1	"5508561".PN.	USPAT	2004/06/07 22:37
-	1	6584029.pn.	USPAT	2004/06/08 10:50
-	1	"4849857".PN.	USPAT	2004/06/08 22:27
-	1	"4908736".PN.	USPAT	2004/06/08 14:54
-	1	"5444301".PN.	USPAT	2004/06/08 14:54
-	1	"5583375".PN.	USPAT	2004/06/08 14:54
-	1	"5767571".PN.	USPAT	2004/06/08 14:55
-	1	"5770888".PN.	USPAT	2004/06/08 14:55
-	1	"5801439".PN.	USPAT	2004/06/08 14:55
-	1	"5821615".PN.	USPAT	2004/06/08 14:55
-	1	"5849608".PN.	USPAT	2004/06/08 14:55
-	1	"4849857".PN.	USPAT	2004/06/08 14:56
-	1	"3657610".PN.	USPAT	2004/06/08 15:11
-	1	"4191905".PN.	USPAT	2004/06/08 15:11
-	1	"4266156".PN.	USPAT	2004/06/08 15:11
-	1	"4405875".PN.	USPAT	2004/06/08 15:11
-	1	"4604644".PN.	USPAT	2004/06/08 15:11
-	1	"4661192".PN.	USPAT	2004/06/08 15:11
-	1	"4699682".PN.	USPAT	2004/06/08 15:11
-	1	"4734608".PN.	USPAT	2004/06/08 15:12
-	1	"4736128".PN.	USPAT	2004/06/08 15:12
-	1	"4737742".PN.	USPAT	2004/06/08 15:12
-	1	"4864470".PN.	USPAT	2004/06/08 15:12
-	1	"4993000".PN.	USPAT	2004/06/08 15:12
-	1	"5014111".PN.	USPAT	2004/06/08 15:12
-	1	"5090119".PN.	USPAT	2004/06/08 15:12
-	1	"5095240".PN.	USPAT	2004/06/08 15:12
-	1	"5120678".PN.	USPAT	2004/06/08 15:12
-	1	"5252882".PN.	USPAT	2004/06/08 15:12
-	1	"5281883".PN.	USPAT	2004/06/08 15:12
-	1	"5359494".PN.	USPAT	2004/06/08 15:13
-	1	"5390401".PN.	USPAT	2004/06/08 15:13
-	1	"5438305".PN.	USPAT	2004/06/08 15:13
-	1	"5459368".PN.	USPAT	2004/06/08 15:14
-	1	"5471722".PN.	USPAT	2004/06/08 15:14
-	1	"5504980".PN.	USPAT	2004/06/08 15:14
-	1	"5900581".PN.	USPAT	2004/06/08 15:14
-	934	257/676	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 15:16
-	809	257/669	USPAT	2004/06/08 15:44
-	22	"4924291"	USPAT	2004/06/08 15:46
-	42	"5212402"	USPAT	2004/06/08 15:47
-	14	"5969461"	USPAT	2004/06/08 15:48
-	14	"5969461"	USPAT	2004/06/08 15:50
-	14	"5650918"	USPAT	2004/06/08 15:52
-	15	"5977615"	USPAT	2004/06/08 15:55
-	44	"4862322"	USPAT	2004/06/08 16:03
-	1	"5471369".PN.	USPAT	2004/06/08 16:00
-	1	"5646829".PN.	USPAT	2004/06/08 16:01
-	1	"5719436".PN.	USPAT	2004/06/08 16:01
-	1	"5780926".PN.	USPAT	2004/06/08 16:01
-	1	"5877478".PN.	USPAT	2004/06/08 16:02
-	1	"5898220".PN.	USPAT	2004/06/08 16:02
-	1	"6069025".PN.	USPAT	2004/06/08 16:02
-	1	"6069025".PN.	USPAT	2004/06/08 16:02
-	1	"6072243".PN.	USPAT	2004/06/08 16:02
-	1	"6077724".PN.	USPAT	2004/06/08 16:02
-	1	"6087718".PN.	USPAT	2004/06/08 16:02

-	1	"6118176".PN.	USPAT	2004/06/08 16:02
-	1015	257/675	USPAT	2004/06/08 16:25
-	1989	257/786	USPAT	2004/06/08 17:38
-	2861	(semiconductor or die or chip or IC) and (flip or "C4" or solder) and (paddle or die near pad)	USPAT	2004/06/08 16:39
-	2161	((semiconductor or die or chip or IC) and (flip or "C4" or solder) and (paddle or die near pad)) and (encapsulat\$3 or mold\$3 or resin or "under fill")	USPAT	2004/06/08 16:38
-	2156	((semiconductor or die or chip or IC) and (flip or "C4" or solder) and (paddle or die near pad)) and (encapsulat\$3 or mold\$3 or resin)	USPAT	2004/06/08 16:38
-	50	((semiconductor or die or chip or IC) and (flip or "C4" or solder) and (paddle or die near pad)) and (under near fill or "under fill")	USPAT	2004/06/08 16:38
-	1401	(semiconductor or die or chip or IC) and (flip or "C4") and (paddle or die near pad)	USPAT	2004/06/08 16:41
-	3369	257/778	USPAT	2004/06/08 17:38
-	2198	257/778 and (die near pad or paddle or heat)	USPAT	2004/06/08 17:39
-	420	257/778 and (die near pad or paddle)	USPAT	2004/06/08 17:44
-	1	"5212402".PN.	USPAT	2004/06/08 17:41
-	33	"5346857"	USPAT	2004/06/08 17:48
-	7	"5767009"	USPAT	2004/06/08 17:48
-	1	"5477086".PN.	USPAT	2004/06/08 19:28
-	1	"5554569".PN.	USPAT	2004/06/08 19:28
-	1	"5917242".PN.	USPAT	2004/06/08 19:29
-	1	"5982026".PN.	USPAT	2004/06/08 19:29
-	33072	semiconductor near wafer	USPAT	2004/06/08 22:27
-	2022	semiconductor near wafer and scrib\$3	USPAT	2004/06/08 22:46
-	32245	semiconductor near wafer and form\$3	USPAT	2004/06/08 22:47
-	3850	semiconductor near wafer near form\$3	USPAT	2004/06/08 22:47
-	924	semiconductor near wafer near method	USPAT	2004/06/08 22:48